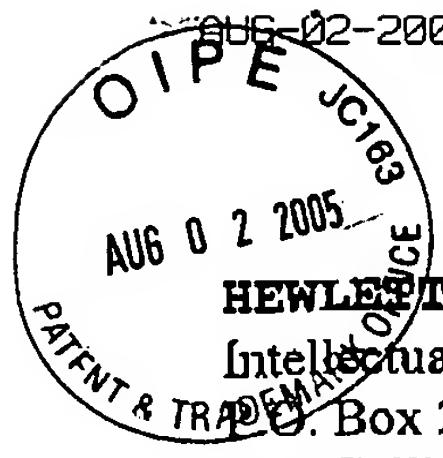


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P.03

HEWLETT-PACKARD COMPANY
Intellectual Property Administration
P.O. Box 272400
Fort Collins, Colorado 80527-2400

PATENT APPLICATION

ATTORNEY DOCKET NO.: 10016669-3

**IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Patent Application of:

Inventor(s): Wayne Kever

Confirmation No.: 5930

Filed: 7/29/2003

Examiner: Berezny, Nema O.

Serial No.: 10/629,055

Group Art Unit: 2813

TITLE: SELECTIVE SOLDER BUMP APPLICATION

Mail Stop: Issue Fees
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

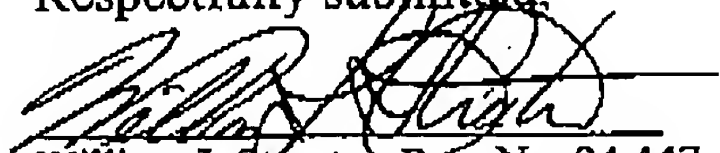
Comments on Statement of Reasons for Allowance

Sir:

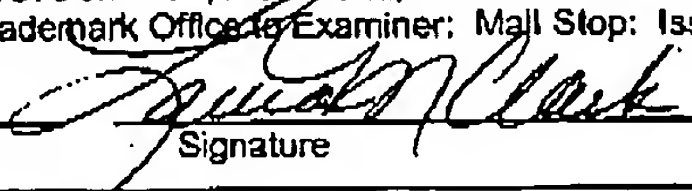
Applicant respectfully submits the following with regard to the examiner's statement of reasons for allowance of claims 23-33. It is Applicant's position that it is the allowed claims that define the scope of coverage to be afforded the invention in this application. Accordingly, the recitation of selected limitations by the examiner should not limit or otherwise affect or abridge the scope of coverage of the allowed claims.

Dated this 2 day of August, 2005.

Respectfully submitted,


William J. Streeter, Reg. No. 24,447
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CERTIFICATE OF MAILING / FAX TRANSMISSION

I hereby certify that this correspondence is, on the date shown below, being:
[] deposited with the U.S. Postal Service as First Class Mail with sufficient postage in an envelope addressed to:
Commissioner for Patents, Mail Stop Amendment, P.O. Box 1450, Alexandria, VA 22313-1450.
[] transmitted by facsimile to the U.S. Patent and Trademark Office Examiner: Mail Stop: Issue Fees; at Fax Number:
(703) 746-4000.
Laura M. Clark
Typed Name

Signature
8/2/2005
Date

AUG-02-2005 14:36

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9708987247 P.01

PATENT APPLICATION

HEWLETT-PACKARD COMPANY
Intellectual Property Administration
Box 272400
Fort Collins, Colorado 80527-2400

ATTORNEY DOCKET NO. 10016669 -3

IN THE

UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Wayne D Kever

Confirmation No.: 5930

Application No.: 10/629055

Examiner: Berezny, Nemo O.

Filing Date: Jul 29, 2003

Group Art Unit: 2813

Title: Selective Solder Bump Application

Mail Stop Issue Fees

Commissioner For Patents

PO Box 1450

Alexandria, VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- () Response/Amendment () Petition to extend time to respond
() New fee as calculated below () Supplemental Declaration
() No additional fee
(X) Other: Comments on Statement of Reasons for Allowance (fee \$)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	11	MINUS	20	= 0	X \$50	\$ 0
INDEP. CLAIMS	1	MINUS	3	= 0	X \$200	\$ 0
[] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$360	\$ 0
EXTENSION FEE	1ST MONTH \$120.00	2ND MONTH \$450.00	3RD MONTH \$1020.00	4TH MONTH \$1590.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

Wayne D Kever

By

William J. Streeter

Attorney/Agent for Applicant(s)

Reg. No. 24,447

Date: August 2, 2005

Telephone No.: (970) 898-3886

Rev 12/04 (TnAmdFax)